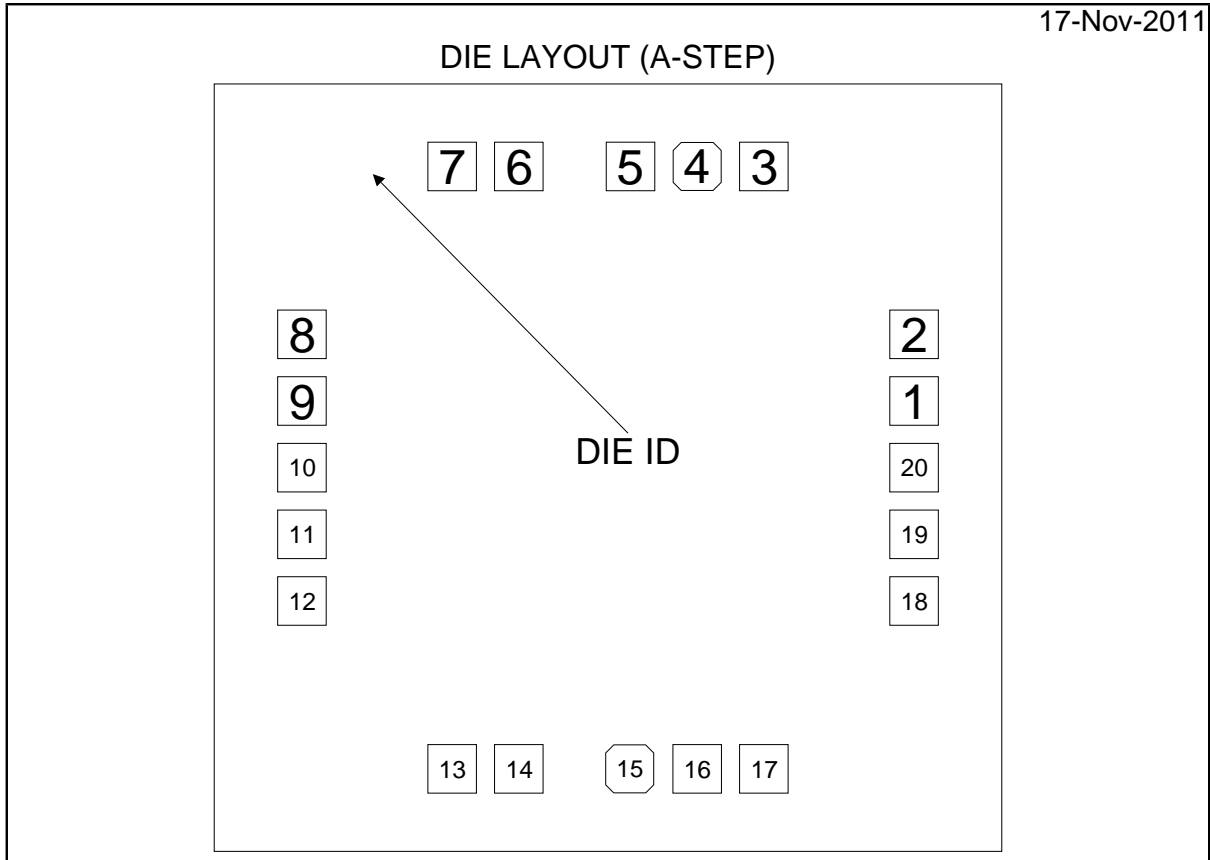


DS90LV031-MDS
3V LVDS Quad CMOS Differential Line Driver



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DS90LV031A	Bond Pad Opening Size (min)	81.90µm x 81.90µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX SOG NITRIDE
Wafer Diameter	203.2mm	Back Side Metal	Bare Back
Die Size (Drawn)	1328.42µm x 1295.40µm 52.3mils x 51.0mils	Back Side Connection	Floating
Thickness	304.8µm Nominal		
Min Pitch	112.50µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(A-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
Din1	1	516.49	112.50	81.90	x	81.90
Dout1+	2	516.49	225.00	81.90	x	81.90
Dout1-	3	263.00	508.27	81.90	x	81.90
NC	4	150.50	508.27	81.00	x	81.00
EN	5	38.00	508.27	81.90	x	81.90
Dout2-	6	-150.50	508.27	81.90	x	81.90
Dout2+	7	-263.00	508.27	81.90	x	81.90
Din2	8	-516.49	225.00	81.90	x	81.90
GND	9	-516.49	112.50	81.90	x	81.90
GND	10	-516.49	0.00	81.90	x	81.90
Din3	11	-516.49	-112.50	81.90	x	81.90
Dout3+	12	-516.49	-225.00	81.90	x	81.90
Dout3-	13	-263.00	-508.27	81.90	x	81.90
EN*	14	-150.50	-508.27	81.90	x	81.90
NC	15	36.65	-508.27	81.00	x	81.00
Dout4-	16	150.50	-508.27	81.90	x	81.90
Dout4+	17	263.00	-508.27	81.90	x	81.90
Din4	18	516.49	-225.00	81.90	x	81.90
Vcc	19	516.49	-112.50	81.90	x	81.90
Vcc	20	516.49	0.00	81.90	x	81.90

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Notes

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